

Title (en)

Method for fusing and connecting solder of IC chip.

Title (de)

Verfahren zum Schmelzen und Verbinden des Lots eines integrierten Schaltungschips.

Title (fr)

Procédé pour fondre et lier de la brasure d'une puce à circuit intégré.

Publication

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Application

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Priority

JP 17141181 A 19811028

Abstract (en)

Disclosed is a method for solder-fusing and connecting an IC chip which comprises locating solder bumps for electric connection, disposed on an IC chip, and a metallic layer for controlling the shape of connecting portions, disposed on the IC chip having said solder bumps and having a melting point higher than the melting point of the solder bumps, to terminals for electric connection and to terminals for controlling the shape of the connecting portions, disposed on a substrate, respectively; heat-fusing the solder bumps to form the connecting portions having the swelling shape at the center; and heat-fusing the metallic layer at a higher temperature to form bumps for controlling the shape of connecting portions, having the swelling shape at the center, and changing the connecting portions having the swelling shape at the center to connecting portions having the contracted shape at the center.

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Cited by

US5023697A; GB2290171A; GB2290171B; EP0732736A3; FR2569052A1; GB2239829A; GB2239829B; WO9912198A1; WO9616442A1

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